

型号: 3EC-M3-VLP

- VLP™系列为低粗糙度的铜箔适用于减成法中的精细线路蚀刻。
VLP™ series as low profile copper foil is suitable for fine-pattern etching in the subtractive process.
- VLP™系列具有高抗拉强度，易于薄型铜箔操作。
High tensile strength, easy to handle thin foil.

用途/Application

- 半导体封装基板
/Semiconductor Package
- 高密度多层基板
/High Density Interconnect
- 柔性电路板
/Flexible Print Board

构成/Composition



生产地点/Production Site

- 日本 / Japan

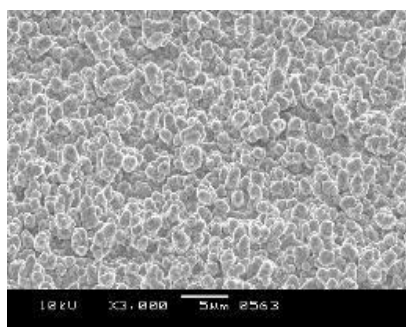
代表性特性数据/Representative data

Model No.	μ m	Area weight (g/m ²)	Laminate side Rz (μ m)	Tensile Strength (N/mm ²)	Elongation (%)	Peel Strength (kg/cm)@FR-4
3EC-M3-VLP	9	80	2.8	500	4	0.9
	12	107	3.0	500	5	1.2
	18	153	3.5	500	8	1.4

※上述列表为代表性数据，非保证数据。

This is representative data, not guaranteed.

处理面/Laminate side



阻剂面/Resist side

